

### Sixpack Open Emitter

### SK50GD066ETp

#### Features\*

- · One screw mounting module
- · Low inductive design
- Press-Fit contact technology
- Fully compatible with other SEMITOP® Press-Fit types
- 600V Trench IGBT3 technology
- Robust and soft switching CAL HD diode technology
- Integrated NTC temperature sensor
- UL recognized, file no. E 63 532

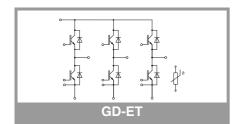
### **Typical Applications**

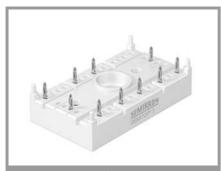
- Motor drives
- Servo drives
- · Air conditioning
- · Auxiliary Inverters
- UPS

Absolute Maximum Ratings						
Symbol	Conditions		Values	Unit		
IGBT 1	•			•		
V <sub>CES</sub>	T <sub>j</sub> = 25 °C		600	V		
Ic	T 150.00	T <sub>s</sub> = 25 °C	53	А		
	T <sub>j</sub> = 150 °C	T <sub>s</sub> = 70 °C	39	Α		
I <sub>C</sub>	T 475.00	T <sub>s</sub> = 25 °C	59	Α		
	− T <sub>j</sub> = 175 °C	T <sub>s</sub> = 70 °C	47	Α		
I <sub>Cnom</sub>		,	50	Α		
I <sub>CRM</sub>			100	Α		
V <sub>GES</sub>			-20 20	V		
t <sub>psc</sub>	$V_{CC} = 360 \text{ V}$ $V_{GE} \le 15 \text{ V}$ $V_{CES} \le 600 \text{ V}$	T <sub>j</sub> = 150 °C	6	μs		
Tj			-40 175	°C		

Absolute Maximum Ratings							
Symbol	Conditions		Values	Unit			
Diode 1	•						
$V_{RRM}$	T <sub>j</sub> = 25 °C		600	V			
I <sub>F</sub>	T <sub>i</sub> = 150 °C	T <sub>s</sub> = 25 °C	46	Α			
	$r_j = 150 \text{ C}$	T <sub>s</sub> = 70 °C	34	Α			
l <sub>F</sub>	T 475 00	T <sub>s</sub> = 25 °C	52	Α			
	− T <sub>j</sub> = 175 °C	T <sub>s</sub> = 70 °C	41	Α			
I <sub>FRM</sub>			100	А			
I <sub>FSM</sub>	10 ms, sin 180°	°, T <sub>j</sub> = 150 °C	320	А			
Ti			-40 175	°C			

Absolute Maximum Ratings						
Symbol	Conditions	Values	Unit			
Module						
I <sub>t(RMS)</sub>	ΔT <sub>terminal</sub> at PCB joint = 30 K, per pin	35	Α			
T <sub>stg</sub>		-40 125	°C			
V <sub>isol</sub>	AC, sinusoidal, t = 1 min	2500	V			





## SEMITOP® 3 Press-Fit

### Sixpack Open Emitter

### SK50GD066ETp

#### Features\*

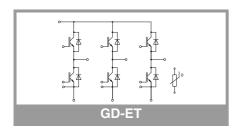
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- Motor drives
- Servo drives
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- UPS

Characte	eristics					
Symbol	Conditions		min.	typ.	max.	Unit
IGBT 1			•			•
V <sub>CE(sat)</sub>	$I_{\rm C} = 50  {\rm A}$	T <sub>j</sub> = 25 °C		1.45	1.85	V
	V <sub>GE</sub> = 15 V chiplevel	T <sub>j</sub> = 150 °C		1.65	2.05	V
$V_{CE0}$	chiplevel	T <sub>j</sub> = 25 °C		0.90	1.10	V
	Chipievei	T <sub>j</sub> = 150 °C		0.80	1.00	V
r <sub>CE</sub>	V <sub>GE</sub> = 15 V	T <sub>j</sub> = 25 °C		11	15	mΩ
	chiplevel	T <sub>j</sub> = 150 °C		17	21	mΩ
$V_{GE(th)}$	$V_{GE} = V_{CE}, I_{C} = 0.8$	mA	5	5.8	6.5	V
I <sub>CES</sub>	$V_{GE} = 0 V$	T <sub>j</sub> = 25 °C			0.05	mA
	$V_{CE} = 600 \text{ V}$			-		mA
C <sub>ies</sub>	.,	f = 1 MHz		3.14		nF
Coes	V <sub>CE</sub> = 25 V V <sub>GF</sub> = 0 V	f = 1 MHz		0.2		nF
C <sub>res</sub>	VGE - O V	f = 1 MHz		0.093		nF
$Q_G$	V <sub>GE</sub> = - 8 V+ 15 V			250		nC
R <sub>Gint</sub>	T <sub>j</sub> = 25 °C			0		Ω
t <sub>d(on)</sub>	$V_{CC} = 300 \text{ V}$	T <sub>j</sub> = 150 °C		28		ns
t <sub>r</sub>	$I_{\rm C} = 50 \text{ A}$	T <sub>j</sub> = 150 °C		32		ns
E <sub>on</sub>	$V_{GE \text{ neg}} = -7 \text{ V}$ $V_{GE \text{ pos}} = 15 \text{ V}$	T <sub>j</sub> = 150 °C		2.2		mJ
t <sub>d(off)</sub>	$R_{G \text{ on}} = 16 \Omega$	T <sub>j</sub> = 150 °C		301		ns
t <sub>f</sub>	$R_{G off} = 16 \Omega$ $di/dt_{on} = 2438 A/\mu s$ $di/dt_{off} = 2438 A/\mu s$	T <sub>j</sub> = 150 °C		45		ns
E <sub>off</sub>				1.73		mJ
R <sub>th(j-s)</sub>	per IGBT, λ <sub>paste</sub> =0.8	8 W/(mK)		1.11		K/W

Characteristics							
Symbol	Conditions		min.	typ.	max.	Unit	
Diode 1						•	
$V_{F}$	I <sub>F</sub> = 50 A	T <sub>j</sub> = 25 °C		1.47	1.87	V	
	chiplevel	T <sub>j</sub> = 150 °C		1.50	1.78	V	
$V_{F0}$	chiplevel	T <sub>j</sub> = 25 °C		0.99	1.10	٧	
		T <sub>j</sub> = 150 °C		0.80	0.89	V	
r <sub>F</sub>	alaialayal	T <sub>j</sub> = 25 °C		9.6	15	mΩ	
	chiplevel	T <sub>j</sub> = 150 °C		14	18	mΩ	
I <sub>RRM</sub>	I <sub>F</sub> = 50 A	T <sub>j</sub> = 150 °C		44		Α	
Q <sub>rr</sub>	$di/dt_{off} = 2438 \text{ A/}\mu\text{s}$	T <sub>j</sub> = 150 °C		4.8		μC	
Err	$V_{GE} = -7 \text{ V}$ $V_{CC} = 300 \text{ V}$	T <sub>j</sub> = 150 °C		0.72		mJ	
R <sub>th(j-s)</sub>	per Diode			1.7		K/W	





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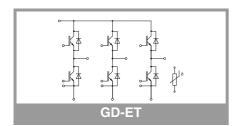
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Characteristics						
Symbol	Conditions	min.	typ.	max.	Unit	
Module						
Ms	to heatsink	2.25		2.5	Nm	
W	weight		30		g	

Characteristics							
Symbol	Conditions	min.	typ.	max.	Unit		
Temperature Sensor							
R <sub>100</sub>	T <sub>r</sub> = 100 °C	493 ± 5%			Ω		
B <sub>100/125</sub>	$R_{(T)}=R_{100}exp[B_{100/125}(1/T-1/T_{100})];T[K];$	3550 ±2%		К			



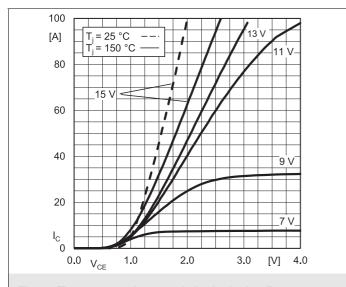


Fig. 1: Typ. output characteristic, inclusive  $R_{\text{CC}'\text{+ EE'}}$ 

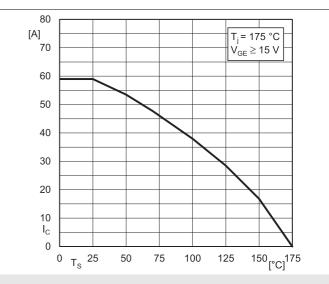


Fig. 2: Typ. rated current vs. temperature  $I_C = f(T_S)$ 

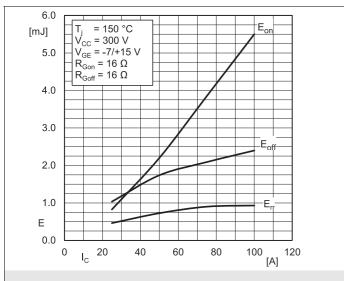


Fig. 3: Typ. turn-on /-off energy =  $f(I_C)$ 

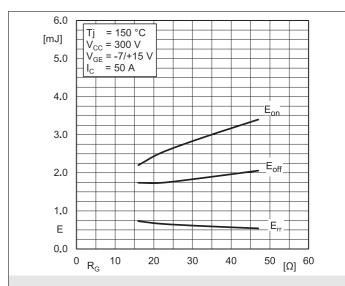


Fig. 4: Typ. turn-on /-off energy = f (R<sub>G</sub>)

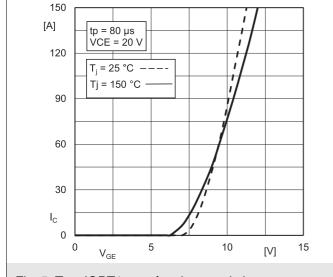


Fig. 5: Typ. IGBT1 transfer characteristic

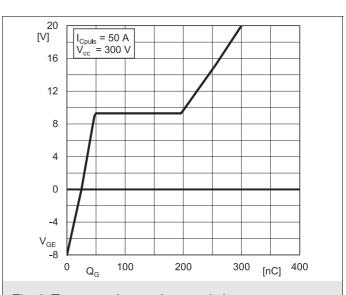


Fig. 6: Typ. gate charge characteristic

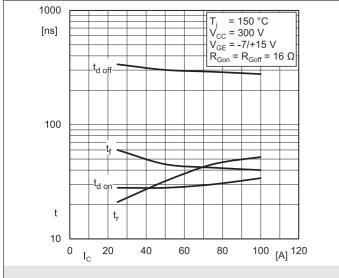


Fig. 7: Typ. switching times vs. I<sub>C</sub>

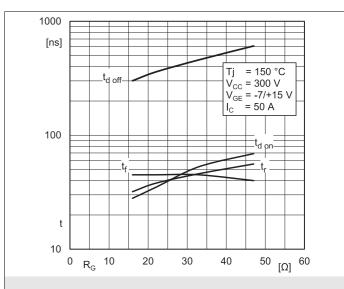


Fig. 8: Typ. switching times vs. gate resistor R<sub>G</sub>

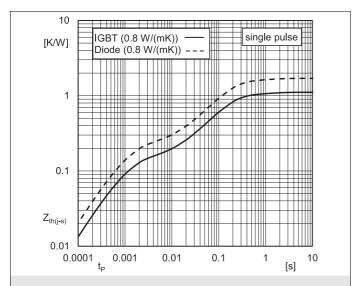


Fig. 9: Typ. transient thermal impedance

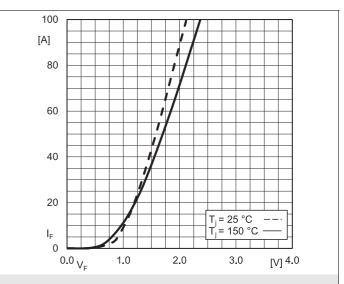
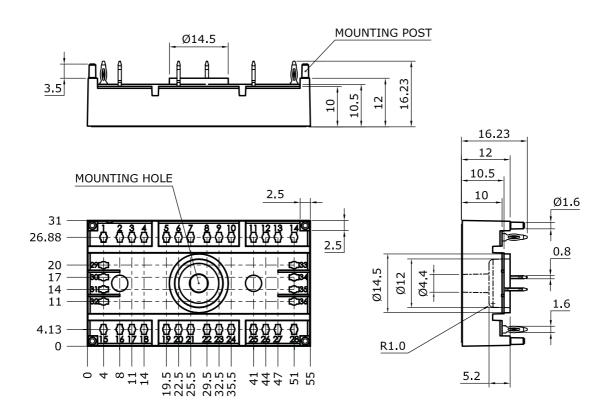


Fig. 10: Typ. CAL diode forward charact., incl.  $R_{CC'+\; EE'}$ 

Dimensions: mm

Tolerance system: ISO 2768-m



Suggested drilled hole diameter for terminal pins in the circuit board:

minimum: 1.575 mmtypical: 1.6 mm

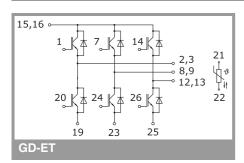
• maximum: 1.625 mm

Suggested hole diameter for the mounting post in the circuit board:

• 2 mm

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### **SEMITOP 3 Press-Fit**



This is an electrostatic discharge sensitive device (ESDS) due to international standard IEC 61340.

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